

## **Materials Declaration Form**

IPC	1752		
Form Type *	Distribute	Version	Z
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		* : Required Field

Supplier Information							
Company Name *	STMicroelectronics	Response Date *	2020-11-16				
Company Unique ID	NL 008751171B01						
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section				
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section				
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION				
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section				
Supplier Comment	Online Technical Support - STMicroelectron http://www.st.com/web/en/support/supp						

## **Uncertainty Statement**

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## Legal Statement

Supplier Acceptance \* true Legal Declaration \* Standard

## Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product							
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date			
SM6T22CAY	AHZJ*TYB022D	AHZJ*TYB022D A		2020-11-16			
	Amount	UoM	Unit type	ST ECOPACK Grade  ECOPACK 2			
	98	mg	Each				
Lommont	ECOPACK® 2 is STMicroelectronics trade na Antimony oxide flame retardant ( in each orga	the contract of the contract o	out Brominated and Chlorinated co	ompound (900ppm) and without			

Manufacturing information						
J-STD-020 MSL Rating						
1	260	3				
<b>Bulk Solder Termination</b>	Terminal Plating	Terminal Base Alloy	Comment	life.augmented		
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00298574	me.augmentea		

	Package Designator	Size	Nbr of instances	Shape	
	Not Applicable 4.54,3.68,2.10		2	shape	
Co	mment	ment SMB CLIP (SOD 6 NEW)			

QueryList: RoHS Directive 2011/65/EU-July 2011 Annex II amended by Delegated Directive 2015/863-March 2015						
	Query					
1 - Product(s) meets EU RoHS requirement v	FALSE					
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)						
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)						
4 - Product(s) does not meet EU RoHS requi	4 - Product(s) does not meet EU RoHS requirements and is not under exemptions					
Exemption Id. Description						
<b>7</b> a	ead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)					

QueryList: ELV directive: 2000/53/EC amended: 2020/363_ March: 2020						
Query Response						
1 - Product(s) meets EU ELV requirements without any exemptions						
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)						
Exemption Id. Description						
8e Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)						

QueryList: California Prop65 list, dated 3rd January 2020						
Query	Response					
1 - The product does not contain identified substance from California Prop 65 List, no exposure to	FALSE					
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to cons	TRUE					
Substance	ubstance amount in product (mg) Application					
Nickel	0.02 die		173			
Lead	8245					

QueryList: REACH-25th June 2020								
	Query							
1 - Product(s) does not contain REACH Subst	tances Of Very High Concern above the limits per the c	definition within REACH		FALSE				
CategoryLevel_Name	ppm in product							
Lead	1000 ppm	0.81	Soft solder	8245				
2 - Product(s) does not contain REACH Su REACH	ubstances Of Very High Concern in any Embedded	article nor Homogeneous Material abo	ove the limits per the definition within	FALSE				
CategoryLevel_Name	CategoryLevel_Name  CategoryLevel_Threshold  CategoryLevel_Threshold  Amount in Embedded Article / Homogeneous Material (mg)  Application - Article / Homogeneous Material							
Lead	ad 1000 ppm 0.808 Soft solder							

Responsible metals sourcing				
Query				
The component is containing at least one of the following metals: Cobalt, Gold, Tantalum, Tin, Tungsten.		true		
The following metals are present is the component : Gold, Told and the component is the com		in,		
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .				

Material Composition Declaration note: Substance present with	tion: ess 0.001mg will not be declared in this documer	nt				Mfr Item Name		AHZJ*TYB022D				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.651	mg	supplier	die	Silicon(Si)	7440-21-3		1.573	mg	952757	16051
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.015	mg	9085	153
				supplier	metallisation	Gold(Au)	7440-57-5		0.009	mg	5451	92
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.017	mg	10297	173
				supplier	passivation	Silicon oxide	7631-86-9		0.009	mg	5451	92
				supplier	polymer coating	Durimide	proprietary		0.028	mg	16959	286
Leadframe	M-004 Copper and its alloys	39.118	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		39.098	mg	999489	398959
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.004	mg	102	41
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.014	mg	358	143
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.002	mg	51	20
Soft solder	Solder	0.878	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	0.808	mg	920273	8245
				supplier	solder	Tin(Sn)	7440-31-5		0.044	mg	50114	449
				supplier	solder	Silver(Ag)	7440-22-4		0.022	mg	25057	224
				supplier	solder	dry flux residue	proprietary		0.004	mg	4556	41
Encapsulation	M-011 Other inorganic materials	54.620	mg	supplier	mold compound	Amorphous silica	7631-86-9		48.339	mg	885004	493255
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		3.277	mg	59996	33439
				supplier	mold compound	Phenolic resin	9003-35-4		2.458	mg	45002	25082
				supplier	mold compound	Carbon black	1333-86-4		0.219	mg	4010	2235
				supplier	mold compound	Magnesium oxide	1309-48-4		0.109	mg	1996	1112
				supplier	mold compound	Aluminium hydroxide	21645-51-2		0.109	mg	1996	1112
				supplier	mold compound	Mercaptopropyl trimethoxysilane	4420-74-0		0.109	mg	1996	1112
connections coating	Solder	1.733	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.733	mg	1000000	17684